
Getting started with STM32F030xx and STM32F070xx series hardware development

Introduction

This application note is intended for system designers who require a hardware implementation overview of the development board features such as the power supply, the clock management, the reset control, the boot mode settings and the debug management. It shows how to use the STM32F0x0xx products family and describes the minimum hardware resources required to develop an application.

This document includes detailed reference design schematics and the description of the main components, interfaces and modes.

Table 1. Applicable products

Type	Part number
Microcontrollers	STM32F030F4, STM32F030CC, STM32F030RC, STM32F030C6, STM32F030K6, STM32F030C8, STM32F030R8, STM32F070C6, STM32F070CB, STM32F070F6, STM32F070RB.

Note: In this document, the notation used for STM32F030xx devices is STM32F030 and the notation used for STM32F070xx devices is STM32F070. When referring to both series the notation STM32F0x0 is used. The pin count and memory size do not impact this hardware description.

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1 Power supplies and reset sources of the STM32F0x0 family

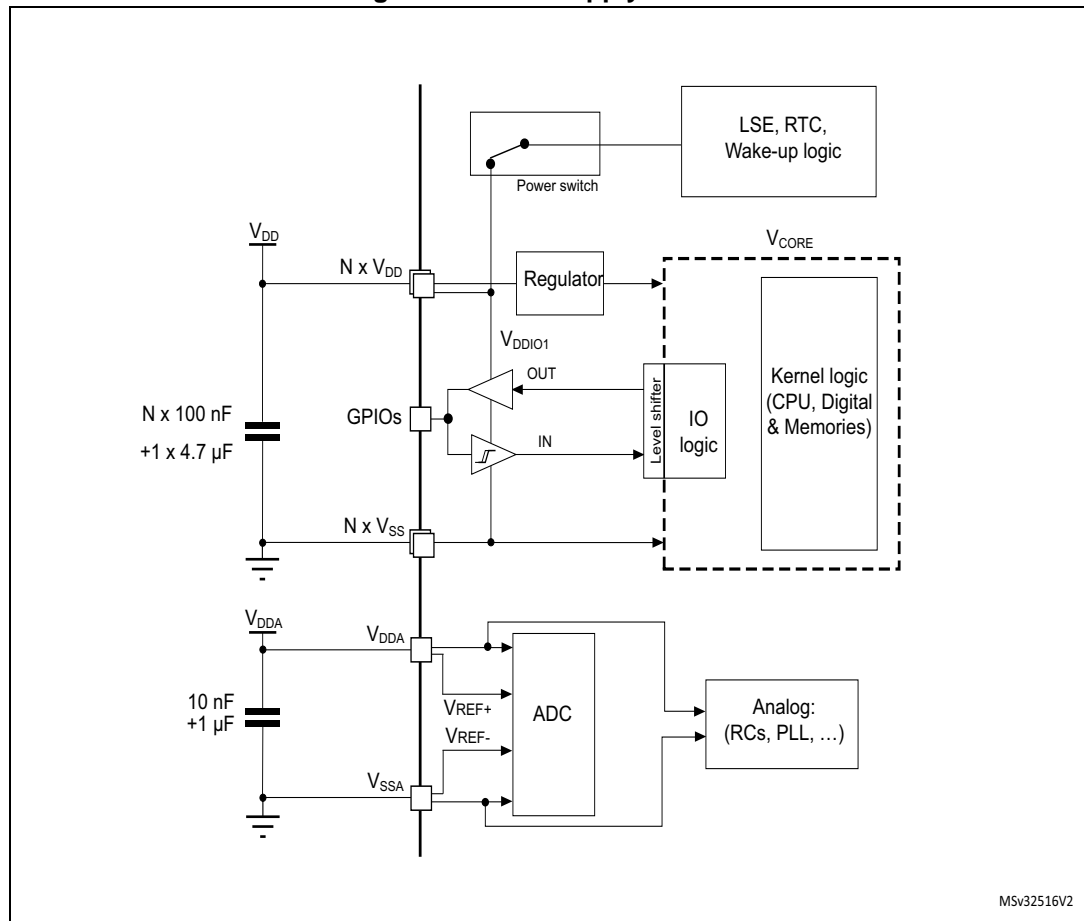
1.1 Power supply schemes

The STM32F0x0 family features different products with different supply schemes. It includes an internal regulator in order to have an internal 1.8 V supply for the core and the digital logic.

There is a variety of power supply schemes:

- V_{DD} from 2.4 V to 3.6 V: external power supply for I/Os and the internal 1.8 V domain. Provided externally through V_{DD} pins.
- V_{DDA} from V_{DD} to 3.6 V: external analog power supply for ADC, Reset blocks, HSI, HSI14, LSI and PLL.
The V_{DDA} voltage level must always be greater than or equal to the V_{DD} voltage level and must be provided first.

Figure 1. Power supply scheme



1.1.1 Independent analog power supply

To improve conversion accuracy and to extend the supply flexibility, the analog domain has an independent power supply which can be separately filtered and shielded from noise on the PCB.

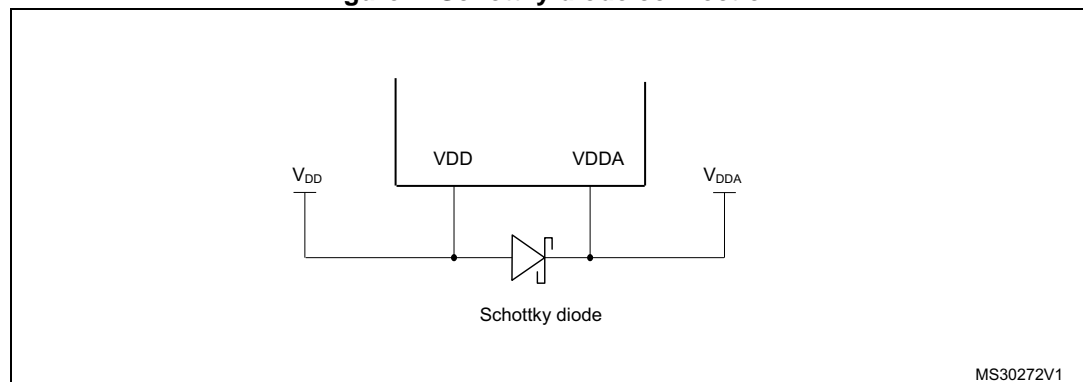
- The ADC voltage supply input is available on a separate VDDA pin.
- An isolated supply ground connection is provided on pin VSSA.

The V_{DDA} supply can be equal to or higher than V_{DD} . This allows V_{DD} to stay low while still providing the full performance for the analog blocks.

When a single supply is used, V_{DDA} must be externally connected to V_{DD} . It is recommended to use an external filtering circuit in order to ensure a noise free V_{DDA} .

When V_{DDA} is different from V_{DD} , V_{DDA} must be always higher or equal to V_{DD} . To keep safe potential difference between V_{DDA} and V_{DD} during power-up/power-down, an external Schottky diode may be used between V_{DD} and V_{DDA} . Refer to the datasheet for the maximum allowed difference.

Figure 2. Schottky diode connection



1.1.2 Voltage regulator

The voltage regulator is always enabled after reset.

It works under two different modes:

- Main (MR) is used in normal operating mode (Run),
- Low power (LPR) can be used in Stop mode where the power demand is reduced.

In standby mode, the regulator is in power-down mode. In this mode, the regulator output is in high impedance and the kernel circuitry is powered down, inducing zero consumption and the loss of the register and SRAM contents. However, the following features are available if configured:

- Independent watchdog (IWDG): the IWDG is started by writing to its Key register or by a hardware option. Once started it cannot be stopped except by a reset.
- Real-time clock (RTC): configured by the RTCEN bit in the RTC domain control register (RCC_BDCR).
- Internal low speed oscillator (LSI): configured by the LSION bit in the Control/Status register (RCC_CSR).
- External 32.768 kHz oscillator (LSE): configured by the LSEON bit in the RTC domain control register (RCC_BDCR).

1.2 Reset and power supply supervisor

1.2.1 Power-on reset (POR) / power-down reset (PDR)

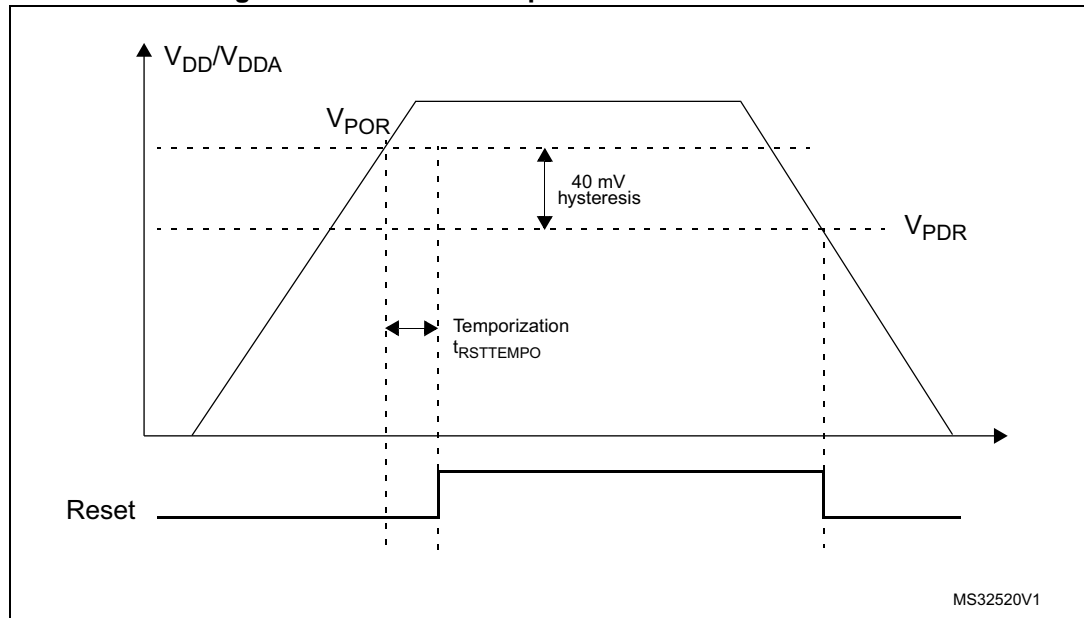
The device has an integrated power-on reset (POR) and power-down reset (PDR) circuits which are always active and ensure proper operation above a threshold of 2.4 V.

The device remains in Reset mode when the monitored supply voltage is below a specified threshold, $V_{POR/PDR}$, without the need for an external reset circuit.

- The POR monitors only the V_{DD} supply voltage. During the startup phase, V_{DDA} must arrive first and be greater than or equal to V_{DD} .
- The PDR monitors both the V_{DD} and V_{DDA} supply voltages. However, the V_{DDA} power supply supervisor can be disabled (by programming a dedicated option bit $V_{DDA_MONITOR}$) to reduce the power consumption if the application design ensures that V_{DDA} is higher than or equal to V_{DD} .

For more details on the power on / power down reset threshold, refer to the electrical characteristics section in the datasheet.

Figure 3. Power on reset/power down reset waveform



1.2.2 System reset

A system reset sets all registers to their reset values, except the reset flags in the clock controller CSR register and the registers in the RTC domain. A system reset is generated when one of the following events occurs:

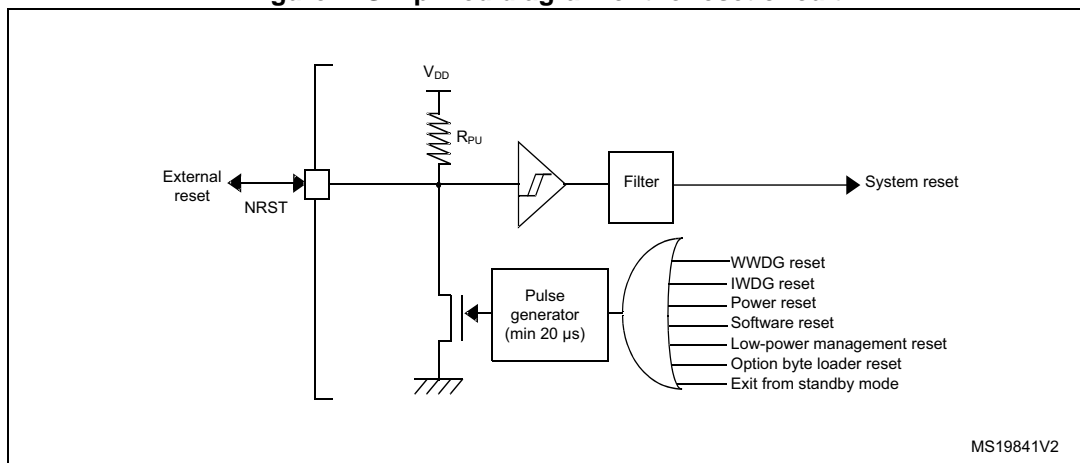
- A low level on the NRST pin (external reset)
- System window watchdog event (WWDG reset)
- Independent watchdog event (IWDG reset)
- A software reset (SW reset)
- Low-power management reset
- Option byte loader reset
- Power reset.

The reset source can be identified by checking the reset flags in the Control/Status register, RCC_CSR.

The RESET service routine vector is fixed at address 0x0000_0004 in the memory map.

The system reset signal provided to the device is output on the NRST pin. The pulse generator guarantees a minimum reset pulse duration of 20 μ s for each internal reset source. In the case of an external reset, the reset is generated while the NRST pin is asserted low.

Figure 4. Simplified diagram of the reset circuit



Software reset

The SYSRESETREQ bit in Cortex-M0 Application Interrupt and Reset Control Register must be set to force a software reset on the device. Refer to the Cortex[®]-M0 technical reference manual for more details.

Low-power mode security reset

To prevent that critical applications mistakenly enter a low-power mode, two low-power mode security resets are available. If enabled in Option bytes, the resets are generated in the following conditions:

- Entering Standby mode: This type of reset is enabled by resetting nRST_STDBY bit in User Option Bytes. In this case, whenever a Standby mode entry sequence is successfully executed, the device is reset instead of entering Standby mode.
- Entering Stop mode: This type of reset is enabled by resetting nRST_STOP bit in User Option Bytes. In this case, whenever a Stop mode entry sequence is successfully executed, the device is reset instead of entering Stop mode.

Option byte loader reset

The option byte loader reset is generated when OBL_LAUNCH (bit 13) is set in the FLASH_CR register. This bit launches the option byte loading by software.

Power reset

A power reset sets all registers to their reset values, except the RTC domain. See [Table 2](#).

RTC domain reset

An RTC domain reset only affects the RTC, LSE and LSI. It is generated when one of the following events occurs. See [Table 2](#).

Table 2. System reset

Modes	Power reset	RTC domain reset
POR/PDR reset	yes	yes
Exiting Standby mode	yes	no
Setting the BDRST bit in RCC_BDCR	no	yes

2 Clocks

Different clock sources can be used to drive the system clock (SYSCLK):

- HSI 8 MHz RC oscillator clock (high-speed internal clock signal)
- HSE oscillator clock (high-speed external clock signal)
- PLL clock

The devices have other secondary clock sources:

- 40 kHz low-speed internal RC (LSI RC) that drives the independent watchdog and, optionally, the RTC used for auto-wakeup from the Stop/Standby modes.
- 32.768 kHz low-speed external crystal (LSE crystal) that optionally drives the RTC.
- HSI 14MHz RC oscillator (HSI14) dedicated for ADC.

Each clock source can be switched on or off independently when it is not used, to optimize the power consumption. Refer to reference manual *STM32F030x4/6/8/C and STM32F070x6/B advanced ARM®-based 32-bit MCUs* (RM0360) for a description of the clock tree.

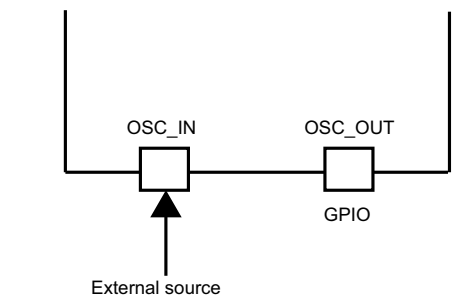
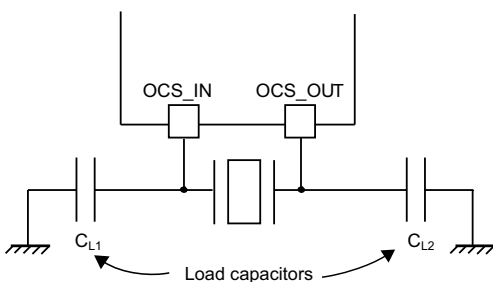
2.1 High speed external clock signal (HSE) OSC clock

The high speed external clock signal can be generated from two possible clock sources:

- HSE external crystal/ceramic resonator
- HSE user external clock.

The resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and the startup stabilization time. The loading capacitance values must be adjusted according to the selected resonator.

Figure 5. HSE/ LSE clock sources

Clock source	Hardware configuration
External clock	 <p style="text-align: right;">MS35507V1</p>
Crystal/Ceramic resonators	 <p style="text-align: right;">MS35508V1</p>

External crystal/ceramic resonator (HSE crystal)

The 4 to 32 MHz external oscillator has the advantage of producing a very accurate frequency on the main clock. Refer to the electrical characteristics section of the datasheet for more details about the associated hardware configuration.

The HSERDY flag in the Clock control register (RCC_CR) indicates if the HSE oscillator is stable or not. At startup, the clock is not released until this bit is set by hardware. An interrupt can be generated if enabled in the Clock interrupt register (RCC_CIR).

The HSE Crystal can be switched on and off using the HSEON bit in the Clock control register (RCC_CR).

External source (HSE bypass)

In this mode, an external clock source must be provided. It can have a frequency of up to 32 MHz. The user selects this mode by setting the HSEBYP and HSEON bits in the [Clock control register \(RCC_CR\)](#). The external clock signal (square, sinus or triangle) with ~40-60% duty cycle depending on the frequency (refer to the datasheet) has to drive the OSC_IN pin while the OSC_OUT pin can be used as a GPIO. See [Figure 5](#).

2.2 LSE clock

The LSE crystal is a 32.768 kHz Low Speed External crystal or ceramic resonator. It has the advantage of providing a low-power but highly accurate clock source to the real-time clock peripheral (RTC) for clock/calendar or other timing functions.

The LSE crystal is switched on and off using the LSEON bit in RTC domain control register (RCC_BDCR). The crystal oscillator driving strength can be changed at runtime using the LSEDRV[1:0] bits in the RTC domain control register (RCC_BDCR) to obtain the best compromise between robustness and short start-up time on one side and low power-consumption on the other.

The LSERDY flag in the RTC domain control register (RCC_BDCR) indicates whether the LSE crystal is stable or not. At startup, the LSE crystal output clock signal is not released until this bit is set by hardware. An interrupt can be generated if enabled in the Clock interrupt register (RCC_CIR).

External source (LSE bypass)

In this mode, an external clock source must be provided. It can have a frequency of up to 1 MHz. The user selects this mode by setting the LSEBYP and LSEON bits in the RTC domain control register (RCC_BDCR). The external clock signal (square, sinus or triangle) has to drive the OSC32_IN pin while the OSC32_OUT pin can be used as GPIO. See [Figure 5](#).

2.3 HSI clock

The HSI clock signal is generated from an internal 8 MHz RC oscillator and can be used directly as a system clock or divided by 2 to be used as PLL input. The HSI RC oscillator has the advantage of providing a clock source at low cost (no external components). It also has a faster startup time than the HSE crystal oscillator however, even with calibration, the frequency is less accurate than an external crystal oscillator or ceramic resonator.

Calibration

The RC oscillator frequencies can vary from one chip to another due to manufacturing process variations, Therefore, it is possible to route the HSI clock to the MCO multiplexer, then the clock can be input to Timer 14 allowing the user to calibrate the oscillator.

2.4 LSI clock

The LSI RC acts as a low-power clock source that can be kept running in Stop and Standby mode for the independent watchdog (IWDG) and RTC. The clock frequency is

around 40 kHz (between 30 kHz and 60 kHz). For more details, refer to the electrical characteristics section of the datasheets.

2.5 ADC clock

The ADC clock is either the dedicated 14 MHz RC oscillator (HSI14) or PCLK divided by 2 or 4. When the ADC clock is derived from PCLK, it is in an opposite phase with PCLK. The 14 MHz RC oscillator can be configured by software either to be turned on/off ("auto-off mode") by the ADC interface or to be always enabled.

2.6 Clock security system (CSS)

The clock security system can be activated by software. In this case, the clock detector is enabled after the HSE oscillator startup delay, and disabled when this oscillator is stopped.

- If a failure is detected on the HSE oscillator clock, the oscillator is automatically disabled.
 - A clock failure event is sent to the break inputs of TIM1 advanced control timer and TIM15, TIM16 and TIM17 general purpose timers.
 - An interrupt is generated to inform the software about the failure (clock security system interrupt CSSI), allowing the MCU to perform recovery operations.
 - CSSI is linked to the Cortex[®]-M0 NMI (non-maskable interrupt) exception vector.
- If the HSE oscillator is used directly or indirectly as the system clock (indirectly means that it is used as the PLL input clock, and the PLL clock is used as the system clock), a detected failure causes a switch of the system clock to the HSI oscillator and the disabling of the external HSE oscillator. If the HSE oscillator clock (divided or not) is the clock entry of the PLL that is being used as a system clock when the failure occurs, the PLL is disabled too.

For details, see the reference manual *STM32F030x4/6/8/C and STM32F070x6/B advanced ARM[®]-based 32-bit MCUs* (RM0360) available from the STMicroelectronics website www.st.com.

3 Boot configuration

In the STM32F0x0, three different boot modes can be selected through the BOOT0 pin and boot configuration bits nBOOT1 in the User option byte, as shown in the following table:

Table 3. Boot modes

Boot mode configuration		Mode
nBOOT1 bit	BOOT0 pin	
x	0	Main Flash memory is selected as boot space ⁽¹⁾
1	1	System memory is selected as boot space
0	1	Embedded SRAM is selected as boot space

1. For STM32F070x6 and STM32F030xC devices, see also Empty check description.

The Boot mode configuration is latched on the 4th rising edge of SYSCLK after a reset. It is up to the user to set Boot mode configuration related to the required Boot mode.

The Boot mode configuration is also re-sampled when exiting from Standby mode. Consequently they must be kept in the required Boot mode configuration in Standby mode. After this startup delay has elapsed, the CPU fetches the top-of-stack value from address 0x0000 0000, then starts code execution from the boot memory at 0x0000 0004.

Depending on the selected boot mode, main Flash memory, system memory or SRAM is accessible as follows:

- **Boot from main Flash memory:** the main Flash memory is aliased in the boot memory space (0x0000 0000), but still accessible from its original memory space (0x0800 0000). In other words, the Flash memory contents can be accessed starting from address 0x0000 0000 or 0x0800 0000.
- **Boot from system memory:** the system memory is aliased in the boot memory space (0x0000 0000), but still accessible from its original memory space (0x1FFF EC00 on STM32F030x4, STM32F030x6 and STM32F030x8 devices, 0x1FFF C400 on STM32F070x6 devices, 0x1FFF C800 on STM32F070xB and 0x1FFF D800 on STM32F030xC devices).
- **Boot from the embedded SRAM:** the SRAM is aliased in the boot memory space (0x0000 0000), but it is still accessible from its original memory space (0x2000 0000).

Empty check

On STM32F070x6 and STM32F030xC devices only, internal empty check flag is implemented to allow easy programming of the virgin devices by the boot loader. This flag is used when BOOT0 pin is defining Main Flash memory as the target boot space. When the flag is set, the device is considered as empty and System memory (boot loader) is selected instead of the Main Flash as a boot space to allow user to program the Flash memory.

This flag is updated only during Option bytes loading: it is set when the content of the address 0x08000 0000 is read as 0xFFFF FFFF, otherwise it is cleared. It means a power on or setting of OBL_LAUNCH bit in FLASH_CR register is needed to clear this flag after programming of a virgin device to execute user code after System reset.

Note: If the device is programmed for a first time but the Option bytes are not reloaded, the device will still select System memory as a boot space after a System reset. The boot loader code is able to detect this situation and will change the boot memory mapping to Main Flash and perform a jump to user code programmed there.

Physical remap

Once the boot mode is selected, the application software can modify the memory accessible in the code area. This modification is performed by programming the MEM_MODE bits in the SYSCFG configuration register 1 (SYSCFG_CFGR1). Unlike Cortex[®] M3 and M4, the M0 CPU does not support the vector table relocation. For application code which is located in a different address than 0x0800 0000, some additional code must be added in order to be able to serve the application interrupts. A solution will be to relocate by software the vector table to the internal SRAM:

- Copy the vector table from the Flash (mapped at the base of the application load address) to the base address of the SRAM at 0x2000 0000.
- Remap SRAM at address 0x0000 0000, using SYSCFG configuration register 1.
- Then once an interrupt occurs, the Cortex[®]-M0 processor will fetch the interrupt handler start address from the relocated vector table in SRAM, then it will jump to execute the interrupt handler located in the Flash.

This operation should be done at the initialization phase of the application. Please refer to application note *STM32F0xx in-application programming using the USART* (AN4065) and attached IAP code from www.st.com for more details.

Embedded boot loader

The embedded boot loader is located in the System memory, programmed by ST during production. It is used to reprogram the Flash memory using one of the following serial interfaces:

- USART on pins PA14/PA15 or PA9/PA10
- I2C on pins PB6/PB7 (STM32F070xx and STM32F030xC devices only)
- USB DFU interface (STM32F070xx devices only)

For further details, please refer to application note *STM32 microcontroller system memory boot mode* (AN2606).

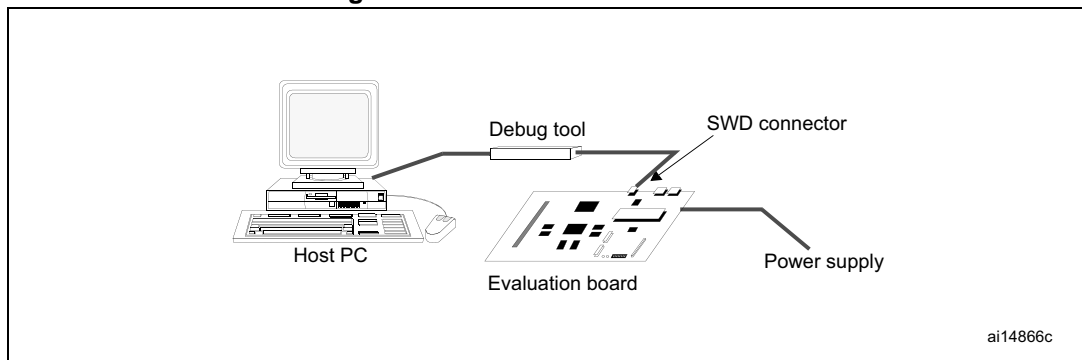
4 Debug management

4.1 Introduction

The host/target interface is the hardware equipment that connects the host to the application board. This interface is made of three components: a hardware debug tool, an SWD connector and a cable connecting the host to the debug tool.

Figure 6 shows the connection of the host to the evaluation board.

Figure 6. Host-to-board connection



4.2 SWD port (serial wire debug)

The STM32F0x0 core integrates the serial wire debug port (SW-DP). It is an ARM® standard CoreSight™ debug port with a 2-pin (clock + data) interface to the debug access port.

4.3 Pinout and debug port pins

The STM32F0x0 MCU is offered in various packages with varying numbers of available pins.

4.3.1 Serial wire debug (SWD) pin assignment

The same SWD pin assignment is available on all STM32F0x0 packages.

Table 4. SWD port pins

SWD pin name	SWD port		Pin assignment
	Type	Debug assignment	
SWDIO	I/O	Serial wire data input/output	PA13
SWCLK	I	Serial wire clock	PA14

4.3.2 SWD pin assignment

After reset (SYSRESETn or PORESETn), the pins used for the SWD are assigned as dedicated pins which are immediately usable by the debugger host.

However, the MCU offers the possibility to disable the SWD, therefore releasing the associated pins for general-purpose I/O (GPIO) usage. For more details on how to disable SWD port, check reference manual *STM32F030x4/6/8/C and STM32F070x6/B advanced ARM®-based 32-bit MCUs* (RM0360) on the section of I/O pin alternate function multiplexer and mapping.

4.3.3 Internal pull-up and pull-down on SWD pins

Once the SWD I/O is released by the user software, the GPIO controller takes control of these pins. The reset states of the GPIO control registers put the I/Os in the equivalent states:

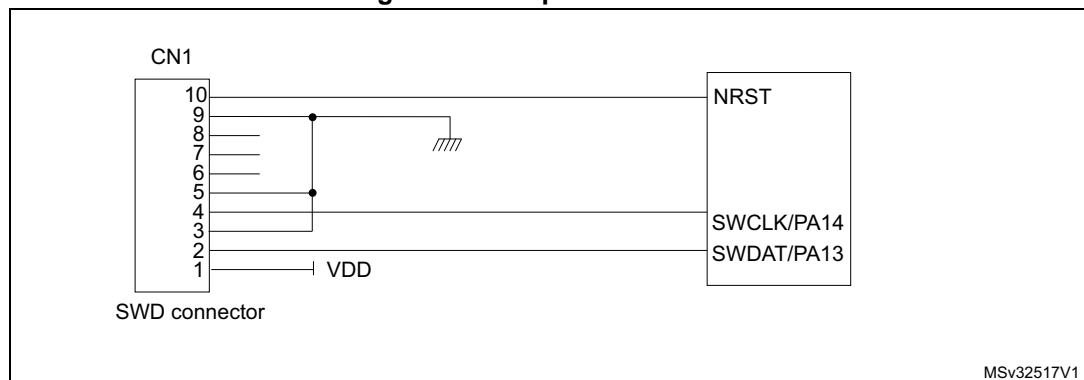
- SWDIO: alternate function pull-up
- SWCLK: alternate function pull-down

Having embedded pull-up and pull-down resistors removes the need to add external resistors.

4.3.4 SWD port connection with standard SWD connector

Figure 7 shows the connection between the STM32F0x0 and a standard SWD connector.

Figure 7. SWD port connection



5 Recommendations

5.1 Printed circuit board

For technical reasons, it is best to use a multilayer printed circuit board (PCB) with a separate layer dedicated to ground (V_{SS}) and another dedicated to the V_{DD} supply. This provides good decoupling and a good shielding effect. For many applications, economical reasons prohibit the use of this type of board. In this case, the major requirement is to ensure a good structure for ground and for the power supply.

5.2 Component position

A preliminary layout of the PCB must make separate circuits:

- High-current circuits
- Low-voltage circuits
- Digital component circuits
- Circuits separated according to their EMI contribution. This will reduce cross-coupling on the PCB that introduces noise.

5.3 Ground and power supply (V_{DD} , V_{DDA})

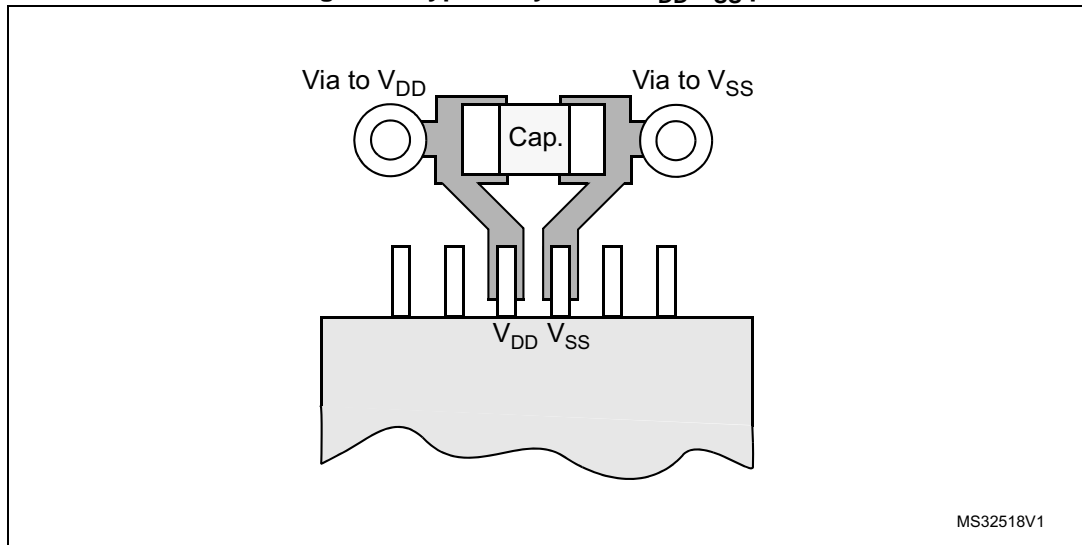
Every block (noisy, low-level sensitive, digital, etc.) should be grounded individually and all ground returns should be to a single point. Loops must be avoided or have a minimum area. In order to improve analog performance, the user must use separate supply sources for V_{DD} and V_{DDA} , and place the decoupling capacitors as close as possible to the device. The power supplies should be implemented close to the ground line to minimize the area of the supplies loop. This is due to the fact that the supply loop acts as an antenna, and is therefore the main transmitter and receiver of EMI. All component-free PCB areas must be filled with additional grounding to create a kind of shielding (especially when using single-layer PCBs).

5.4 Decoupling

All power supply and ground pins must be properly connected to the power supplies. These connections, including pads, tracks and vias should have as low an impedance as possible. This is typically achieved with thick track widths and, preferably, the use of dedicated power supply planes in multilayer PCBs.

In addition, each power supply pair should be decoupled with 100 nF filtering ceramic capacitor and a chemical capacitor of about 4.7 μ F connected between the supply pins of the STM32F0x0 device. These capacitors need to be placed as close as possible to, or below, the appropriate pins on the underside of the PCB. Typical values are 10 nF to 100 nF, but exact values depend on the application needs. [Figure 8](#) shows the typical layout of such a V_{DD}/V_{SS} pair.

Figure 8. Typical layout for V_{DD}/V_{SS} pair



MS32518V1

5.5 Other signals

When designing an application, the EMC performance can be improved by closely studying:

- Signals for which a temporary disturbance affects the running process permanently (such as interrupts and handshaking strobe signals, but not LED commands). For these signals, a surrounding ground trace, shorter lengths and the absence of noisy and sensitive traces nearby (crosstalk effect) improve EMC performance.
- Digital signals: the best possible electrical margin must be reached for the two logical states and slow Schmitt triggers are recommended to eliminate parasitic states.
- Noisy signals (clock, etc.)
- Sensitive signals (high impedance, etc.)

5.6 Unused I/Os and features

All microcontrollers are designed for a variety of applications and often a particular application does not use 100% of the MCU resources.

To increase EMC performance and avoid extra power consumption, unused clocks, counters or I/Os, should not be left free. I/Os should be connected to a fixed logic level of 0 or 1 by an external or internal pull-up or pull-down on the unused I/O pin. The other option is to configure GPIO as output mode using software. Unused features should be frozen or disabled, which is their default value.

6 Reference design

6.1 Description

The reference design shown in [Figure 9](#), introduces the STM32F0x0, a highly integrated microcontroller running at 48 MHz, that combines the Cortex[®]-M0 32-bit RISC CPU core with 64 Kbytes of embedded Flash memory and 8 Kbytes of SRAM.

6.1.1 Clock

Two clock sources are used for the microcontroller:

- HSE: X1– 8 MHz crystal for the STM32F0x0 microcontroller
- LSE: X2– 32.768 kHz crystal for the embedded RTC

Refer to [Section 2: Clocks on page 11](#).

6.1.2 Reset

The reset signal in [Figure 9](#) is active low. The reset sources include:

- Reset button (B1)
- Debugging tools via the connector CN1

Refer to [Section 1.2.2: System reset on page 9](#).

6.1.3 Boot mode

The boot option is configured by setting BOOT0 through switch SW1 and option bit nBOOT1. Refer to [Section 3: Boot configuration on page 15](#).

6.1.4 SWD interface

The reference design shows the connection between the STM32F0x0 and a standard SWD connector. Refer to [Section 4: Debug management on page 17](#).

Note: *It is recommended to connect the reset pin in order to be able to reset the application from the tool.*

6.1.5 Power supply

Refer to [Section 1.1: Power supply schemes on page 6](#).

6.1.6 Pinouts and pin description

Please refer to the STM32F0x0 datasheets available on www.st.com for the pinout information and pin description of each device.

6.2 Component references

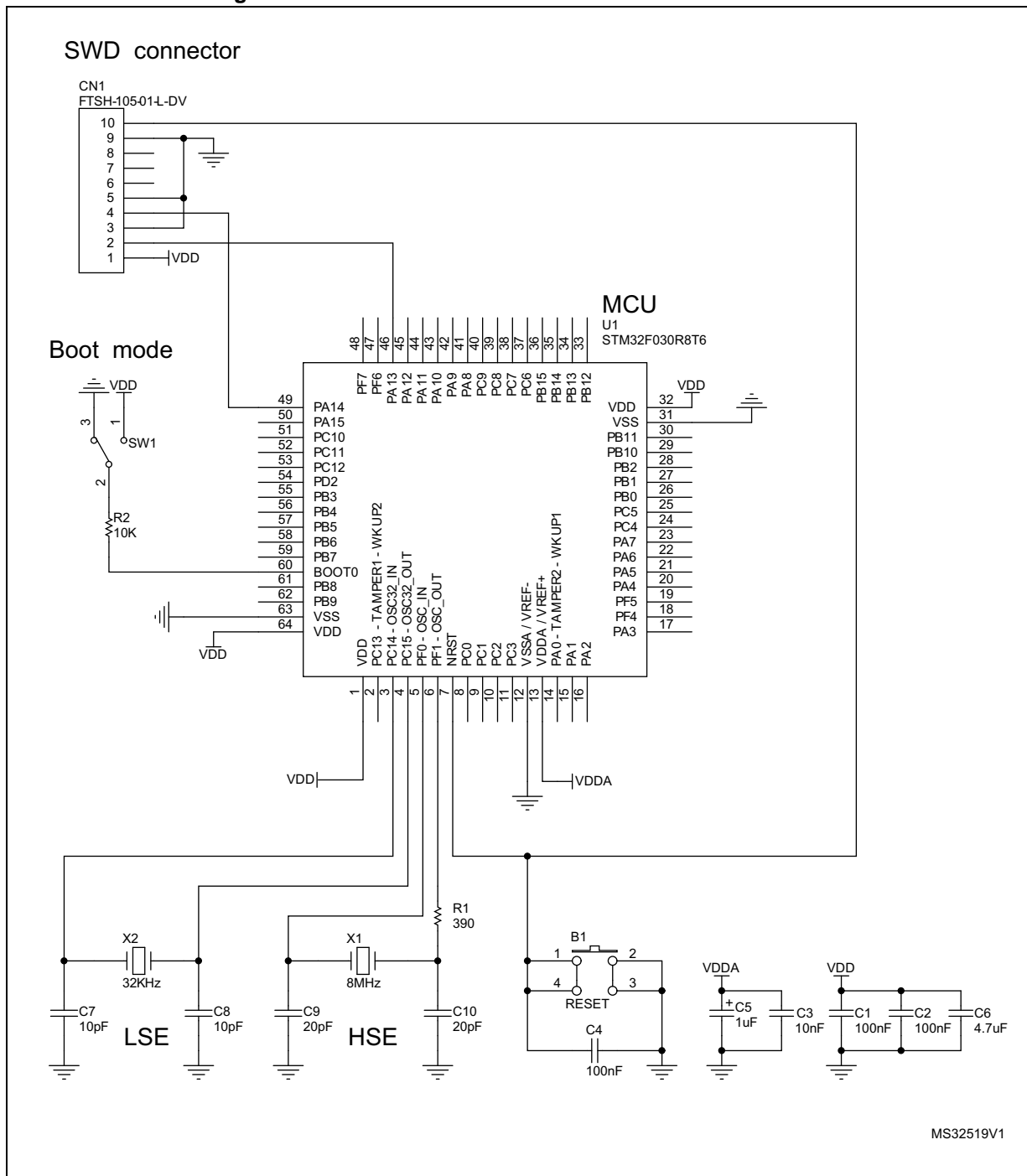
Table 5. Mandatory components

Component	Reference	Value	Quantity	Comments
Microcontroller	U1	STM32F030R8T6	1	64-pin package.
Capacitor	C1/C2	100 nF	2	Ceramic capacitors (decoupling capacitors).
Capacitor	C3	10 nF	1	Ceramic capacitor (decoupling capacitor).
Capacitor	C5	1 μ F	1	Used for VDDA.
Capacitor	C6	4.7 μ F	1	Used for VDD.

Table 6. Optional components

Component	Reference	Value	Quantity	Comments
Resistor	R1	390 Ω	1	Used for HSE: the value depends on the crystal characteristics. This value is given only as a typical example.
Resistor	R2	10 K Ω	1	Used for BOOT0 pin.
Capacitor	C4	100 nF	1	Ceramic capacitor for RESET button.
Capacitor	C7/C8	10 pF	2	Used for LSE: the value depends on the crystal characteristics.
Capacitor	C9/C10	20 pF	2	Used for HSE: the value depends on the crystal characteristics.
Quartz	X1	8 MHz	1	Used for HSE.
Quartz	X2	32 kHz	1	Used for LSE.
Switch	SW1	-	1	Used to select the correct boot mode.
Push-button	B1	-	1	Used as reset button.
SWD connector	CN1	FTSH-105-01-L-DV	1	Used for program/debug of the MCU.

Figure 9. STM32F030 microcontroller reference schematic



7 Hardware migration from STM32F1 series to STM32F0x0 devices

The entry-level STM32F030 and general-purpose STM32F1xxx families are pin-to-pin compatible. All peripherals shares the same pins in the two families, but there are some minor differences between packages.

The transition from the STM32F1 series to the STM32F030 devices is simple as only a few pins are impacted. The impacted pins are shown in **bold** in [Table 7](#).

Table 7. STM32F1 and STM32F030 series pinout differences⁽¹⁾

Package		STM32F1 series	STM32F030 devices
LQFP64	LQFP48	Pinout	Pinout
1	1	VBAT	VDD
5	5	PD0 - OSC_IN	PF0 - OSC_IN
6	6	PD1 - OSC_OUT	PF1 - OSC_OUT
18	-	VSS_4	PF4
19	-	VDD_4	PF5
28	20	BOOT1 - PB2	PB2
47	35	VSS_2	PF6
48	36	VDD_2	PF7

1. Highlighted in **bold** the impacted pins of the transition between STM32F1 series to STM32F030 devices.

8 Revision history

Table 8. Document revision history

Date	Revision	Changes
10-Nov-2014	1	Initial release.
01-Apr-2016	2	Added the support for STM32F070xx along the document.

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